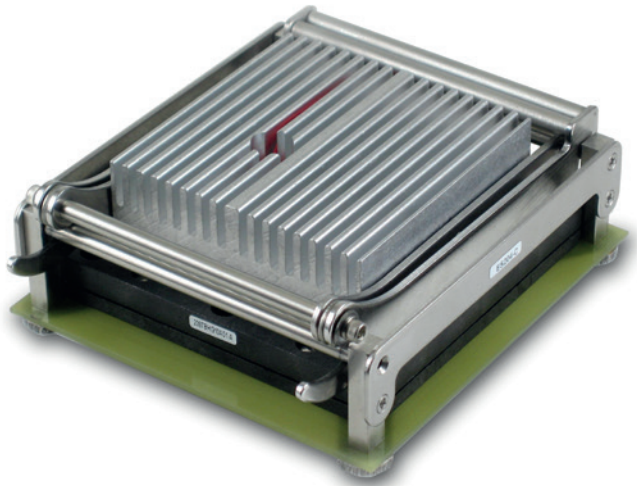


ES-Series H-Pin Socket

Accelerated life testing solution



ES family Series of sockets extended the scope of a burn-in socket. The modular lid construction can handle up to 1 kW of power and is optimized with thermal simulation to ensure out-of-the-box performance whether liquid or air cooled.

Leveraging a variety of advanced manufacturing techniques and industry-leading automation enables the lowest cost of test. Our patented H-Pin technology provides versatility in the socket application which can be used for ATE and SLT functional testing, in addition to covering the full gambit of burn-in test applications. The ES family Series of sockets is designed for use with all advanced burn-in systems. With adaptation comes unmatched value in delivering cutting-edge technology.

ES-Series product meets the demanding requirements of next-generation AI, datacenter, and network accelerator applications as these cutting-edge devices get larger and more powerful. The ES socket modularity allows for the platform to evolve with each new generation of device.

Burn-in sockets using H-Pin technology for high-reliability testing of next-generation IC packages

Benefits

- Configurable design, large tooling catalogue, moulding, machining, 3D printing, and assembly automation deliver best-in-class quality, price, and lead times.
- An extensive catalogue of standard components provides field-tested designs.
- Double-latching clamshell provides ease of use during operation for high pin count applications.
- Thermal and electrical simulation, Monte Carlo and FEA all ensure the delivery of out-of-the-box solution.

Feature Options

- Spring loaded plunger
- Heat sink
- HAST venting features
- Integrated thermal control with heater and sensor
- Reverse seating plane
- Maximum component clearance under the DUT
- High temperature materials for above 200 °C applications

ES Series socket specifications

Mechanical properties

- **Pitch:** 0.40 mm minimum
- **Package size:**
 - LGA: 27 mm to 100 mm
 - BGA: 27 mm to 100 mm
- **7000+**
- **Temperature:** -55 °C to 260 °C

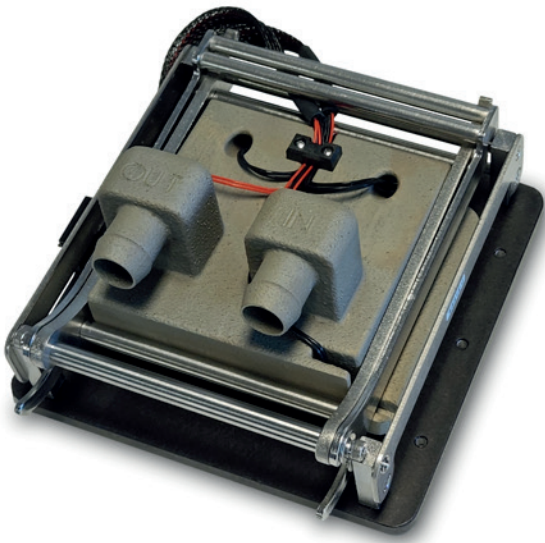
Electrical properties

- **Contact resistance:** 35 mΩ
- **Current carrying capacity:** up to 4 A

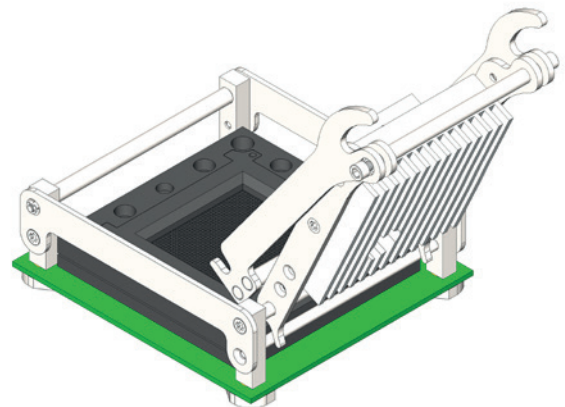
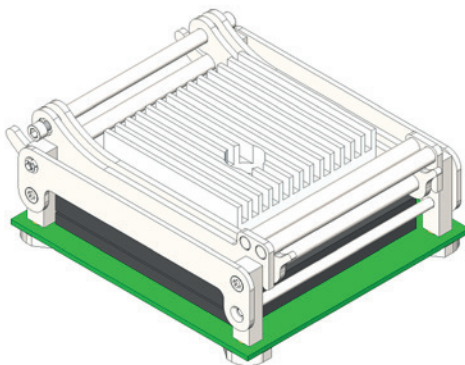
Materials

- **Contact:** BeCu/Au plated
- **Spring:** SS/Au plated
- **Socket:** Engineering plastics

ES Series socket dimensions



Liquid cooled heatsink option



Heat sink, heater and RTD, spring loaded pusher

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